





Applicable standard					
Rating	Operating temperature range 	-55°C to + 105°C(Note 1)	Storage temperature range	-10°C to + 60°C(Note 3)	
	Operating humidity range	40% to + 80%(Note 2)	Storage humidity range	40% to + 70%(Note 3)	
	Voltage	250V AC/DC	Applicable connector	DF3-*S-2C	
	Current	AWG 22 to 24 : 3A AWG 26 : 2A AWG 28 : 1A	UL • CSA rating	Voltage	30V AC/DC
Specifications					
Item		Test method		Requirements	QT AT
Construction					
General examination		Visually and by measuring instrument.		According to drawing.	X X
Marking		Confirmed visually.			X X
Electric characteristics					
Contact Resistance Millivolt Level Method		20mV MAX, 1mA (DC or 1000Hz).		30mΩ MAX.	X —
Insulation resistance		500V DC.		1000MΩ MIN.	X —
Voltage proof		650V AC for 1 min.		No flashover or breakdown.	X —
Mechanical characteristics					
Mechanical operation		50 times insertions and extractions.		① Contact resistance: 30mΩ MAX. ② No damage, crack or looseness of parts.	X —
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.		① No electrical discontinuity of 1μs. ② No damage, crack or looseness of parts.	X —
Shock		490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.		① No electrical discontinuity of 1μs. ② No damage, crack or looseness of parts.	X —
Environmental characteristics					
Rapid change of temperature		Temperature -55°C→ +85°C Time 30min→ 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.)		① Contact resistance: 30mΩ MAX. ② Insulation resistance: 1000MΩ MIN. ③ No damage, crack or looseness of parts.	X —
Damp heat (Steady state)		Exposed at 40 ± 2 °c, 90 to 95 %, 96 h.		① Contact resistance: 30mΩ MAX. ② Insulation resistance: 500MΩ MIN. ③ No damage, crack or looseness of parts.	X —
Resistance to Soldering heat		1) Reflow soldering Number of reflow cycles : 2 cycles MAX. Duration above 230°C, 60 sec. MAX. Peak temperature: 250°C 10 sec. MAX. Pre-heat temperature :150 to 180°C Pre-heat time : 90 to 120 sec. 2) Manual soldering Soldering iron temperature :300°C, Soldering time : 3sec. No strength on contact.		No deformation of case of excessive looseness of the terminals.	X —
Solderability		Soldering temperature :230 °C Soldering time :3s.		A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed.	X —
Remarks					
Note 1:Include the temperature rising by current.					
Note 2:No condensing					
Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation.					
Note 4:Apply to crimping contact type.					
	Count	Description of revisions	Designed	Checked	Date
	1	DIS-H-00001874	HT. SATO	TS. FUKUSHIMA	16. 07. 22
Unless otherwise specified, refer to IEC 60512.			Approved	KI. AKIYAMA	15. 12. 17
			Checked	TS. FUKUSHIMA	15. 12. 17
			Designed	HT. SATO	15. 12. 17
			Drawn	MI. SAKIMURA	15. 12. 17
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-367142-51-00
	Specification sheet		Part no.	DF3EA-*P-2V (51)	
	Hirose electric co., ltd.		Code no.	CL543	 1/1